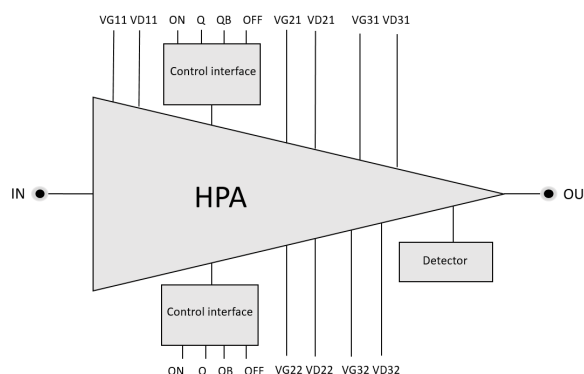


6-18 GHz High Power Amplifier

GaN Monolithic Microwave IC

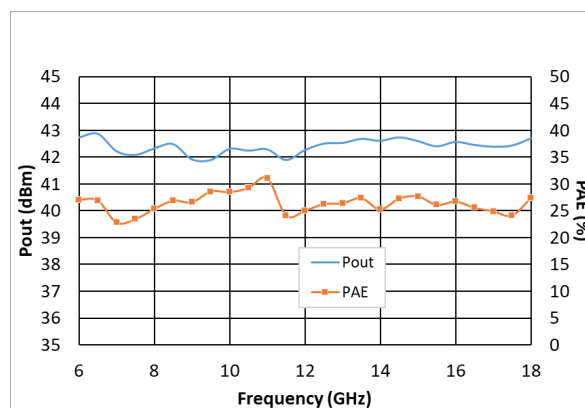
Description

The CHA8618-99F is a monolithic GaN High Power Amplifier in the frequency band 6-18GHz with a control interface for fast switching. This driver provides 42.5 dBm of Output Power. The circuit exhibits a small signal gain of 33dB. The overall power supply is of 20V/1.2A (quiescent current). It is designed for a wide range of applications, for military systems, such as electronic warfare, and test instrumentation. The part is manufactured on robust GaN HEMT technology and is available as a bare die.



Main Features

- Broadband performances: 6-18GHz
- Linear Gain = 33dB
- Pout = 42.5dBm for +23dBm Input Power
- Id associated current = 3.6A
- DC bias: Vd=20V @Idq = 1.2A
- 3.6x5.6mm²



Main Electrical Characteristics

Tbackside = +25°C

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	6		18	GHz
Gain	Linear Gain		33		dB
Psat	Output Power @saturation (Pin = 23dBm)		42.5		dBm
Id	Drain current @saturation (Pin = 23dBm)		3.6		A

Specifications

Tbackside = +25°C, Vd = +20V, Idq = 1.2A

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	6		18	GHz
Gain	Linear Gain		33		dB
Psat	Output Power @saturation (Pin = 23dBm)		42.5		dBm
Id	Drain current @saturation (Pin = 23dBm)		3.6		A
S11	Input return loss		-15		dB
S22	Output return loss		-12		dB
Idq	Quiescent current		1.2		A
Vd	Drain voltage		20		V
Vg	Gate voltage		-2.7		V

These values are representative of measurements done in test fixture with a bonding wire of typically 0.25nH to 0.3nH.

Absolute Maximum Ratings ⁽¹⁾

Tbackside = +25°C

Symbol	Parameter	Values	Unit
Vd	Drain bias voltage	27	V
Pin	Maximum peak input power overdrive	25	dBm

⁽¹⁾ Operation of this device above any one of these parameters may cause permanent damage.

Recommended Operating Range

Tbackside = +25°C

Symbol	Parameter	Values	Unit
Vd	Drain bias voltage	10-20	V
Idq	Maximum quiescent drain bias current	1.2	A
Pin	Maximum peak input power overdrive	23	dBm
Tj	Maximum Junction temperature ⁽²⁾	200	°C

These values are representative of measurements done in test fixture with a bonding wire of typically 0.25nH to 0.3nH.

⁽²⁾ See Device thermal performances section page 5/20

Temperature Range

Tcase	Operating temperature range	-40 to +85	°C
Tstg	Storage temperature range	-55 to +150	°C

Typical Bias Conditions

Two biasing procedures are available:

1. By using standard VG biasing
2. By using the control interface

Standard VG biasing

Tbackside=+25°C

Symbol	Pad N°	Parameter	Values	Unit
VG11	40	Gate voltage tuned for $I_{dq} \approx 1.2A$	-2.7	V
VG21	32	Gate voltage tuned for $I_{dq} \approx 1.2A$	-2.7	V
VG31	15	Gate voltage tuned for $I_{dq} \approx 1.2A$	-2.7	V
VD11	38	1 st stage drain voltage	20	V
VD21	30	2 nd stage drain voltage	20	V
VD31	26	3 rd stage drain voltage	20	V

“Power ON” sequence

1. Bias HPA gate voltage close to $V_{pinch-off}$ (Typically: $VG11 = VG21 = VG31 \sim -5V$)
2. Apply VD bias voltage (Typically: $VD = VD11 = V21 = V31 = 20V$)
3. Increase VG up to quiescent bias drain current I_{dq}
4. Apply RF signal

“Power OFF” sequence

1. Turn off RF signal
2. Bias HPA gate voltage at VG close to $V_{pinch-off}$ (Typically: $VG11 = VG21 = VG31 \sim -5V$)
3. Turn VD bias voltage to 0V
4. Turn VG bias voltage to 0V

Typical Bias Conditions

Control interface

Tbackside=+25°C

Symbol	Pad N°	Parameter	Values	Unit
VGON	37	Gate voltage tuned for Idq ≈ 1.2A	~ -2.7V	V
VGOFF	33	Gate pinch off voltage	-5	V
VD11	38	1 st stage drain voltage	20	V
VD21	30	2 nd stage drain voltage	20	V
VD31	26	3 rd stage drain voltage	20	V

Truth table

Driver State	Q	QB	VGON	VGOFF
Mode ON	-4V	-11V	~ -2.7V	-5V
Mode OFF	-11V	4V	~ -2.7V	-5V

“Power ON” sequence

1. HPA gate voltage at VGON & VGOFF close to Vpinch-off (Typically: VG ≈ -5V)
2. Bias PA gate voltage at QB = -11V
3. Bias PA gate voltage at Q = -4V
4. Apply VD bias voltage (Typically: VD11 = VD21 = VD31 = 20V)
5. Increase VGON up to quiescent bias drain current Idq
6. Apply RF signal

“Power OFF” sequence

1. Turn off RF signal
2. Bias HPA gate voltage at VGON close to Vpinch-off (Typically: VG ≈ -5V)
3. Turn VD bias voltage to 0V
4. Turn VGON bias voltage to 0V
5. Turn VGOFF bias voltage to 0V
6. Turn Q & QB voltage to 0V

Device thermal performances

All the figures given in this section are obtained assuming that the die is only cooled down by conduction through the chip backside.

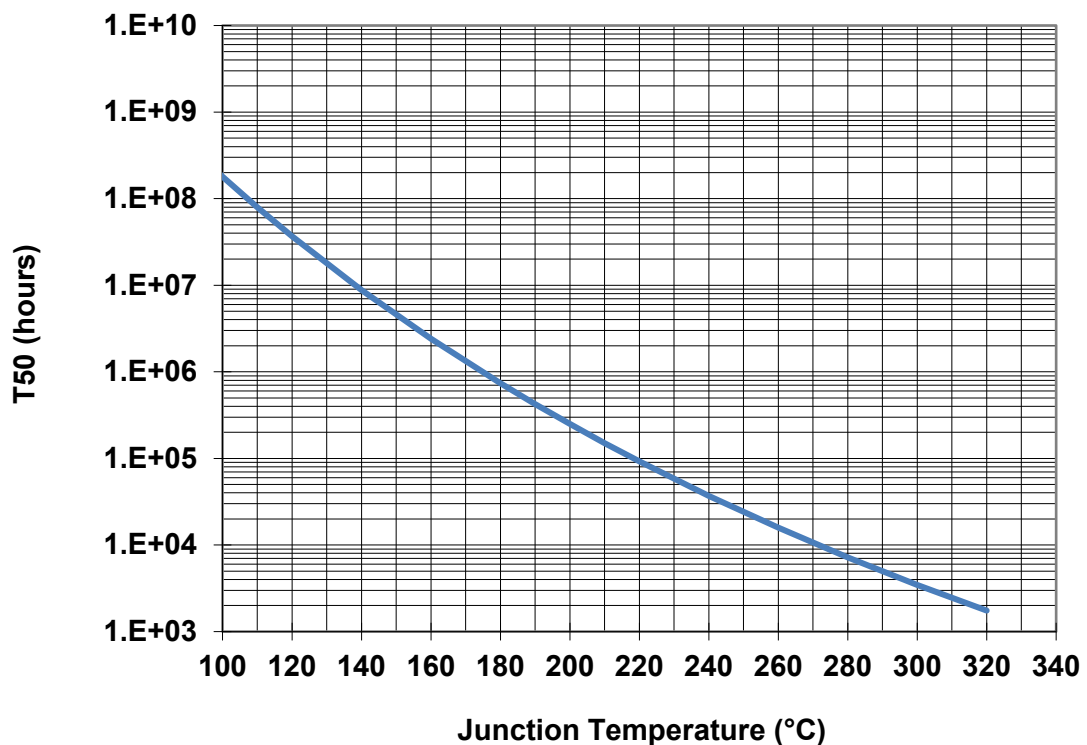
The temperature is monitored at the chip back-side interface (T_{backside}).

For nominal operating, the system maximum temperature must be adjusted in order to guarantee that T_{junction} remains below the maximum value specified in the Recommended Operating Ratings table.

So, the system PCB must be designed to comply with this requirement.

Parameter	Biasing conditions	T _{junction} (°C)	R _{TH} (°C/W)	T ₅₀ (hours)
R _{TH} ⁽¹⁾ Thermal Resistance (Junction to Case)	V _d = 20V P _{out} = 42.5dBm P _{diss} = 56.5W	200	2.04	1.05E+05

¹ Assuming 85°C T_{backside}



Typical On wafer measurements: Sij parameters

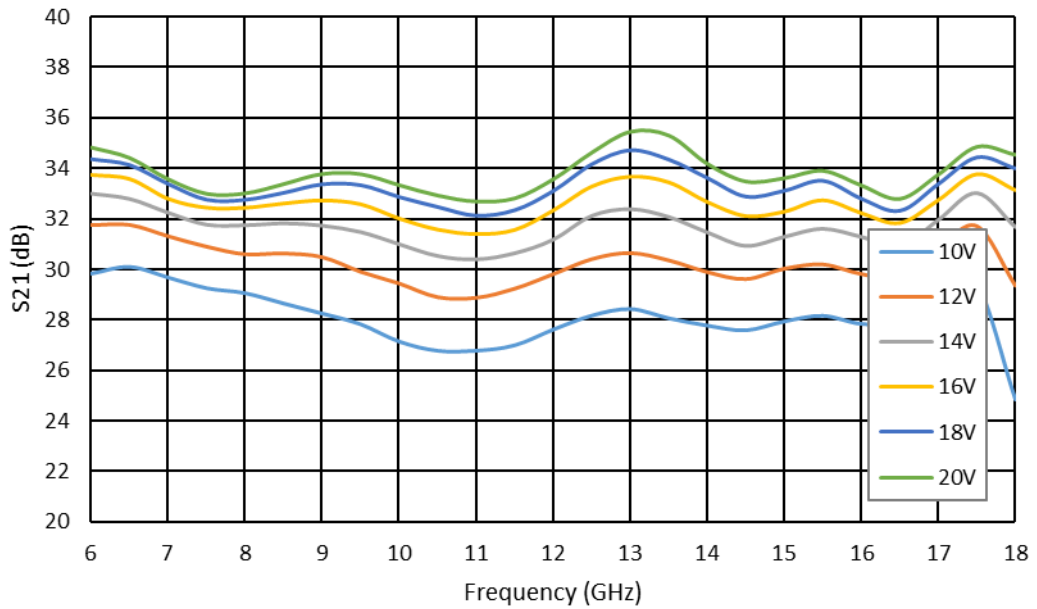
Tbackside=+25°C, Vd = +20V, Idq = 1.2A

Freq (GHz)	S11 (dB)	PhS11 (°)	S21 (dB)	PhS21 (°)	S12 (dB)	PhS12 (°)	S22 (dB)	PhS22 (°)
6	-9.67	-169.94	33.26	-46.41	-84.97	-0.76	-4.49	179.97
6.5	-11.66	-172.22	32.60	-106.68	-69.21	-163.26	-8.07	159.53
7	-13.88	-166.91	31.81	-157.11	-74.62	-103.47	-10.54	148.79
7.5	-14.78	-154.76	31.57	157.57	-74.00	-94.45	-12.62	133.19
8	-14.16	-143.59	31.78	112.80	-68.83	165.77	-14.99	100.02
8.5	-12.72	-144.52	32.21	66.52	-71.08	127.62	-16.49	45.32
9	-12.03	-152.18	32.45	19.16	-67.30	-38.55	-14.31	-6.55
9.5	-12.74	-160.07	32.25	-29.10	-71.44	-2.79	-11.50	-44.81
10	-14.29	-160.46	31.66	-74.17	-72.45	101.89	-9.12	-67.60
10.5	-15.43	-152.16	31.14	-116.07	-78.25	-69.76	-8.07	-88.50
11	-15.06	-140.35	30.91	-156.22	-69.25	176.40	-7.00	-108.21
11.5	-13.21	-135.40	31.12	164.70	-62.54	-81.24	-6.47	-125.09
12	-11.76	-136.46	31.76	123.98	-66.71	-133.56	-6.67	-145.04
12.5	-10.42	-144.08	32.79	81.38	-68.50	-96.48	-7.42	-171.34
13	-9.53	-153.28	33.77	32.64	-72.56	-31.34	-9.23	164.43
13.5	-9.22	-168.17	34.38	-20.30	-67.17	-120.84	-10.75	134.30
14	-10.06	175.07	34.19	-74.44	-70.98	124.39	-13.32	94.97
14.5	-12.38	158.67	33.31	-127.66	-69.95	178.61	-13.84	45.63
15	-16.60	144.91	32.17	-175.85	-78.01	153.58	-11.32	-0.10
15.5	-25.09	137.35	31.36	137.99	-77.21	160.50	-9.80	-27.40
16	-31.19	-87.35	31.12	93.00	-66.95	164.07	-8.03	-50.20
16.5	-20.52	-85.61	31.50	44.62	-74.18	-30.25	-6.98	-67.93
17	-17.16	-108.22	32.28	-9.58	-75.26	-143.56	-5.91	-83.93
17.5	-19.87	-113.85	32.98	-72.23	-65.59	153.75	-6.39	-101.35
18	-18.24	-65.98	33.00	-142.12	-62.92	82.84	-8.21	-116.40

Typical Evaluation Board measurements

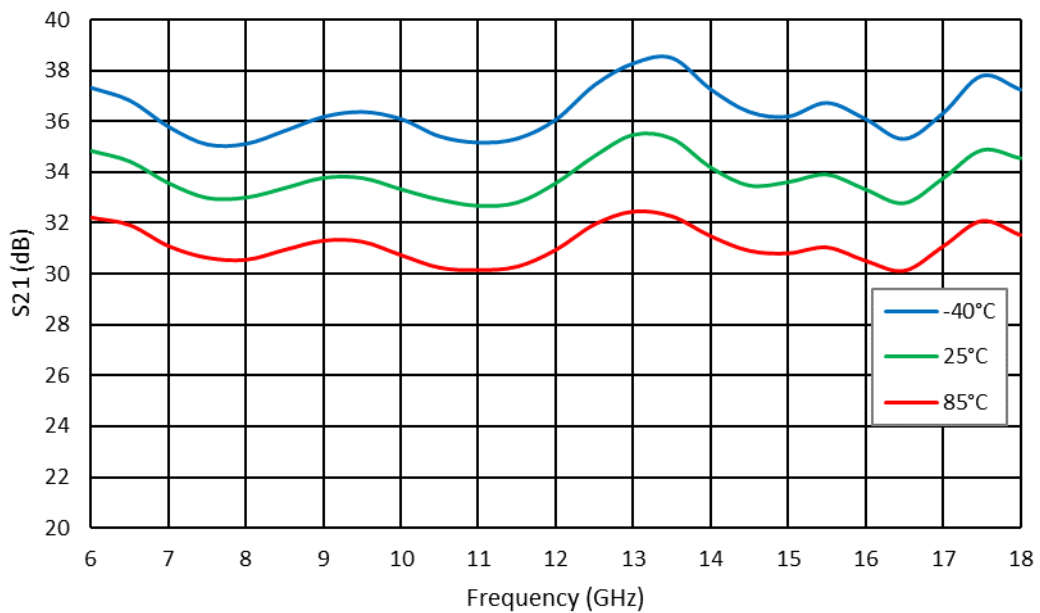
Tbackside = +25°C; Vd = 10, 12, 14, 16, 18 & 20V, Idq = 1.2A

Linear Gain S21 (dB) vs Frequency (GHz) and drain voltage variation



Tbackside = -40°C, +25°C & 85°C; Vd = +20V, Idq = 1.2A @ 25°C

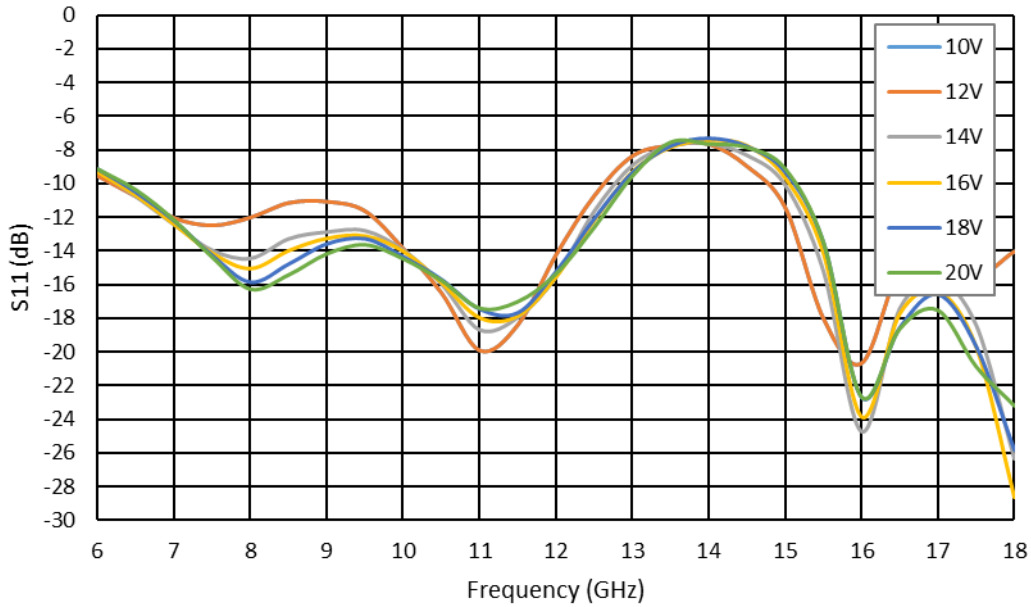
Linear Gain S21 (dB) vs Frequency (GHz) and drain temperature variation



Typical Evaluation Board measurements

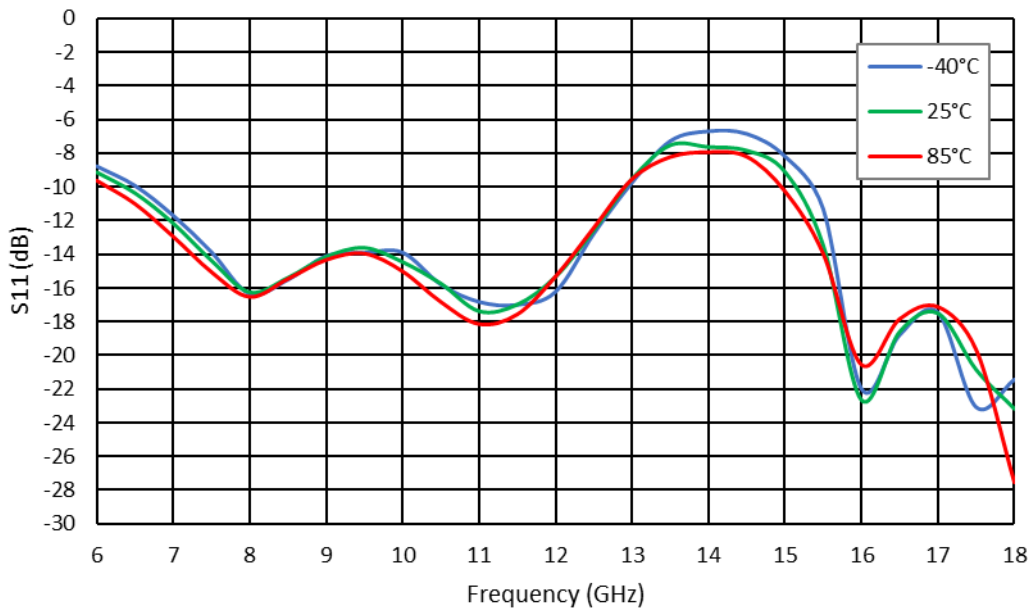
Tbackside = +25°C; Vd = 10, 12, 14, 16, 18 & 20V, Idq = 1.2A

Input return loss S11 (dB) vs Frequency (GHz) and drain voltage variation



Tbackside = -40°C, +25°C & 85°C; Vd = +20V, Idq = 1.2A @ 25°C

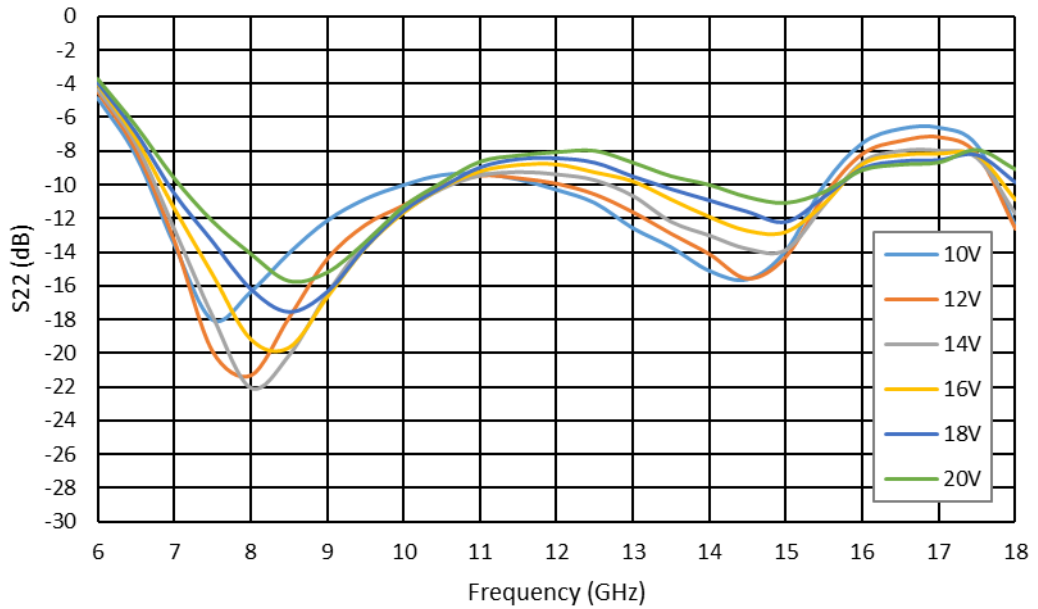
Input return loss S11 (dB) vs Frequency (GHz) and temperature variation



Typical Evaluation Board measurements:

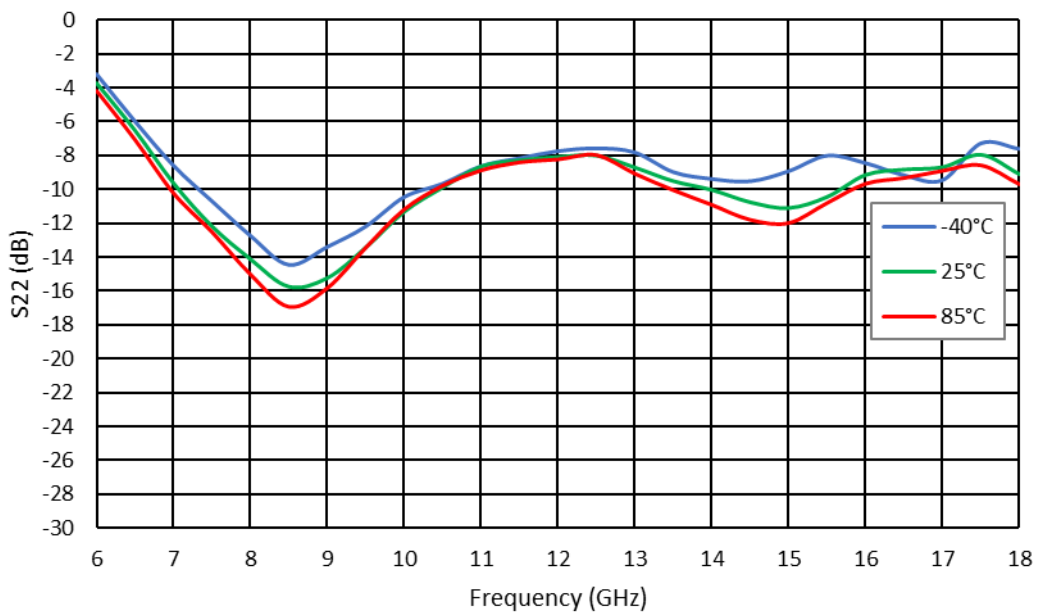
Tbackside = +25°C ; Vd = 10, 12, 14, 16, 18 & 20V, Idq = 1.2A

Output return loss S22 (dB) vs Frequency (GHz) and drain voltage variation



Tbackside = -40°C, +25°C & 85°C; Vd = +20V, Idq = 1.2A @ 25°C

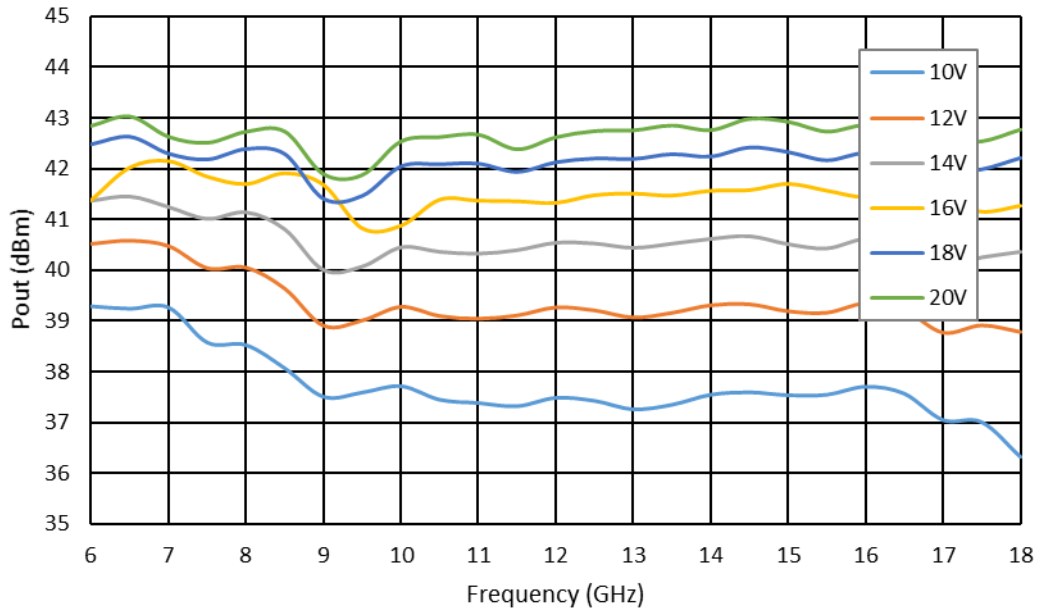
Output return loss S22 (dB) vs Frequency (GHz) and temperature variation



Typical Evaluation Board measurements

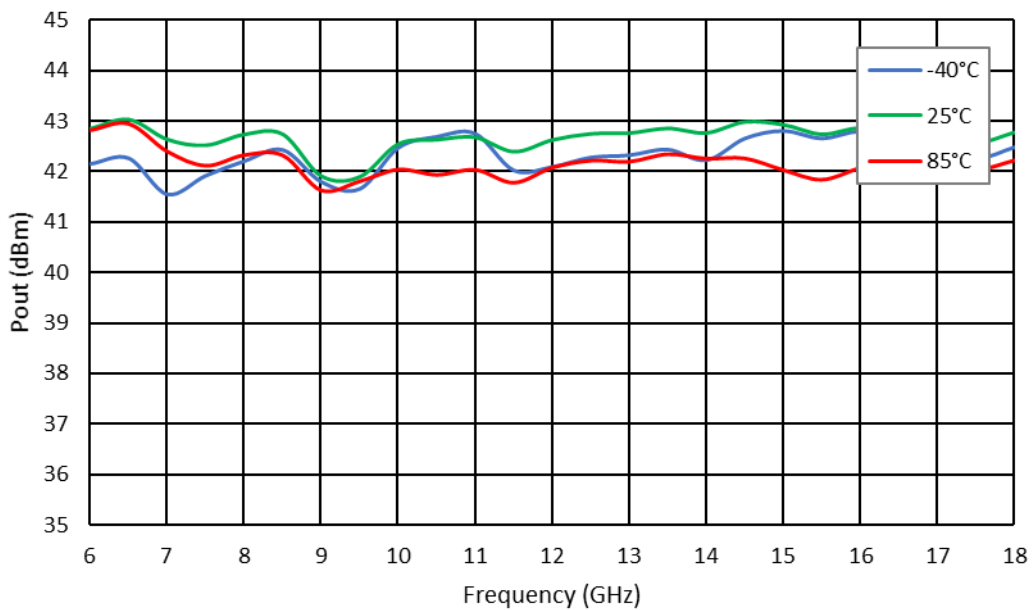
Tbackside = +25°C, Vd = +20V, Idq = 1.2A@ 25°C; Pin = 23dBm

Pout (dBm) vs Frequency (GHz) and drain voltage variation



Tbackside = -40°C, +25°C & 85°C; Vd = +20V, Idq = 1.2A @ 25°C; Pin = 23dBm

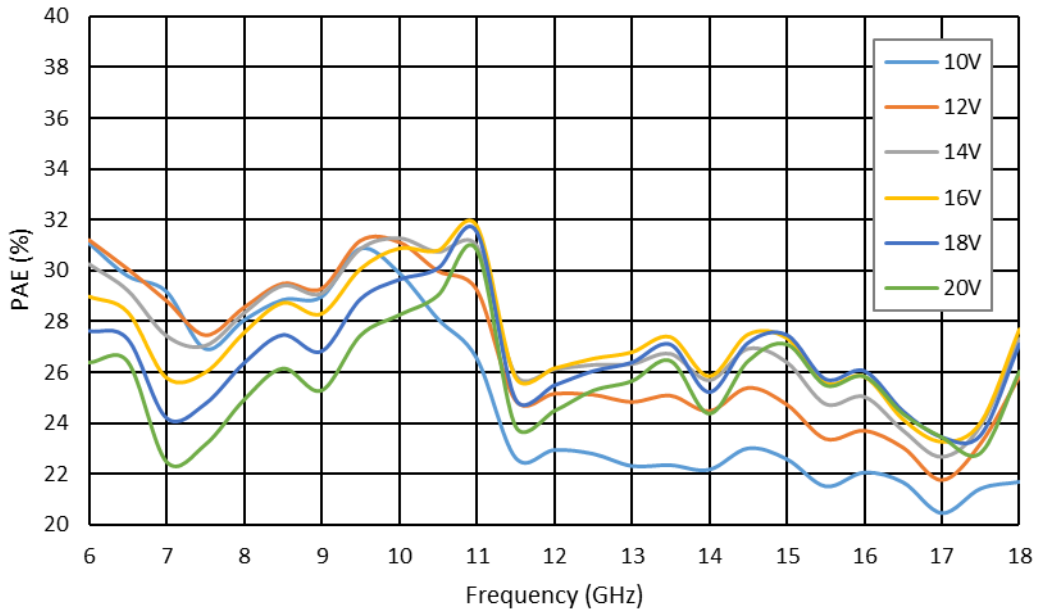
Pout (dBm) vs Frequency (GHz) and temperature variation



Typical Evaluation Board measurements

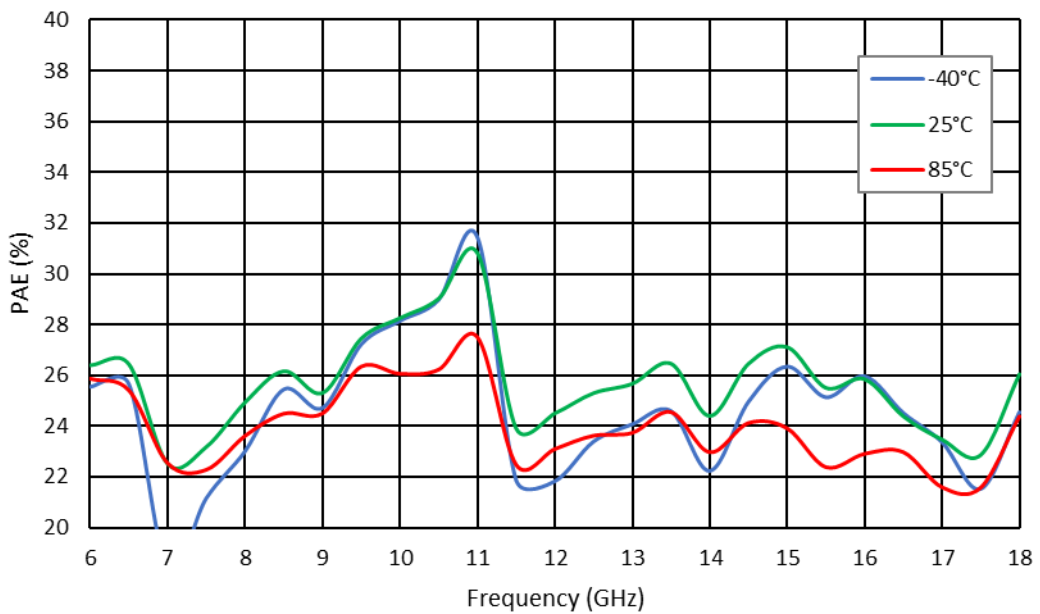
Tbackside = +25°C, Vd = +20V, Idq = 1.2A @25°C; Pin = 23dBm

PAE (%) vs Frequency (GHz) and drain voltage variation



Tbackside = -40°C, +25°C & 85°C; Vd = +20V, Idq = 1.2A @ 25°C; Pin = 23dBm

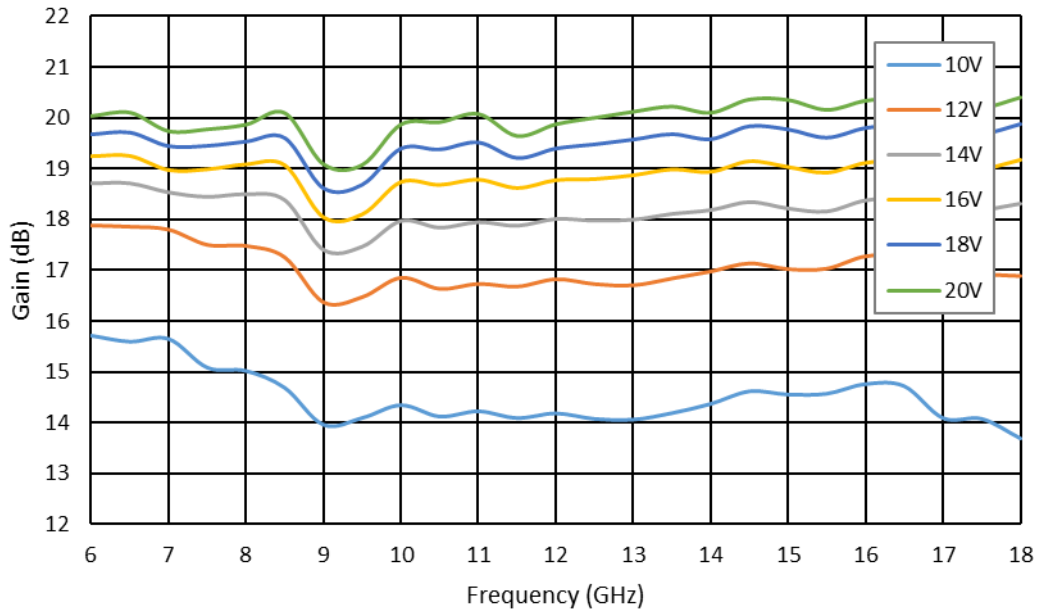
PAE (%) vs Frequency (GHz) and temperature variation



Typical Evaluation Board measurements

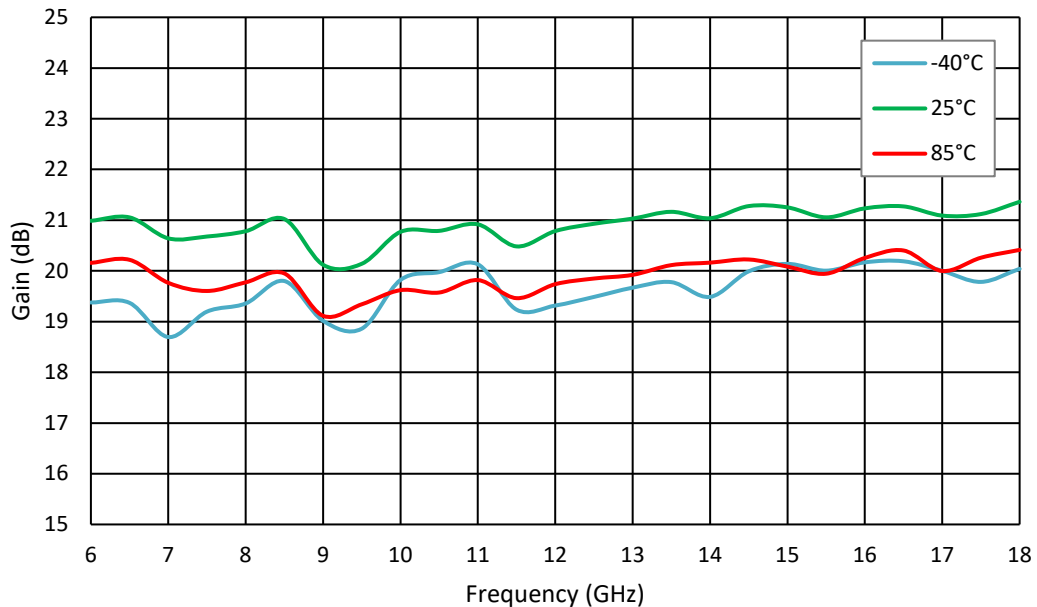
Tbackside = 25°C, Vd = 10, 12, 14, 16, 18 & 20 V, Idq = 1.2A; Pin = 23dBm

Gain (dB) vs Frequency (GHz) and drain voltage variation



Tbackside = -40°C, +25°C & 85°C; Vd = +20V, Idq = 1.2A @ 25°C; Pin = 23dBm

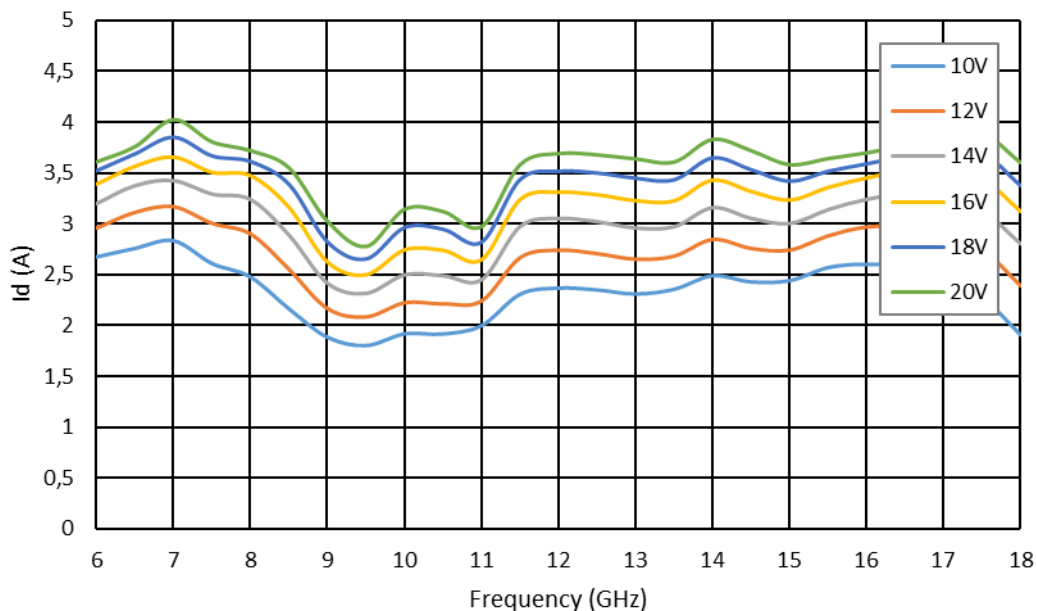
Gain (dB) vs Frequency (GHz) and temperature variation



Typical Evaluation Board measurements

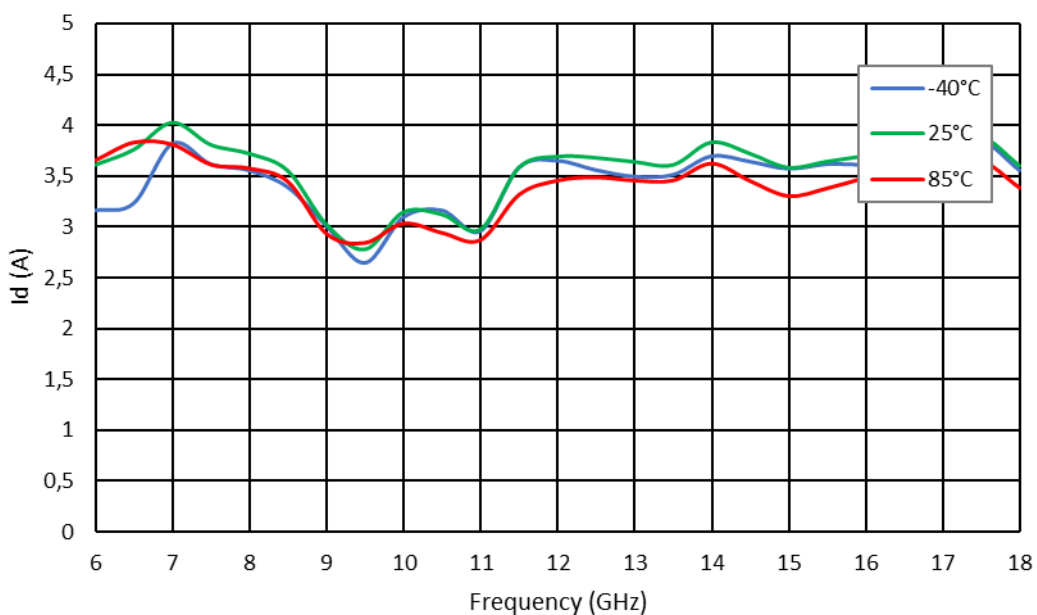
Tbackside = +25°C, Vd = 10, 12, 14, 16, 18 & 20V, Idq = 1.2A @25°C; Pin = 23dBm

Id (A) vs Frequency (GHz) and voltage variation



Tbackside = -40°C, +25°C & 85°C; Vd = +20V, Idq = 1.2A @ 25°C; Pin = 23dBm

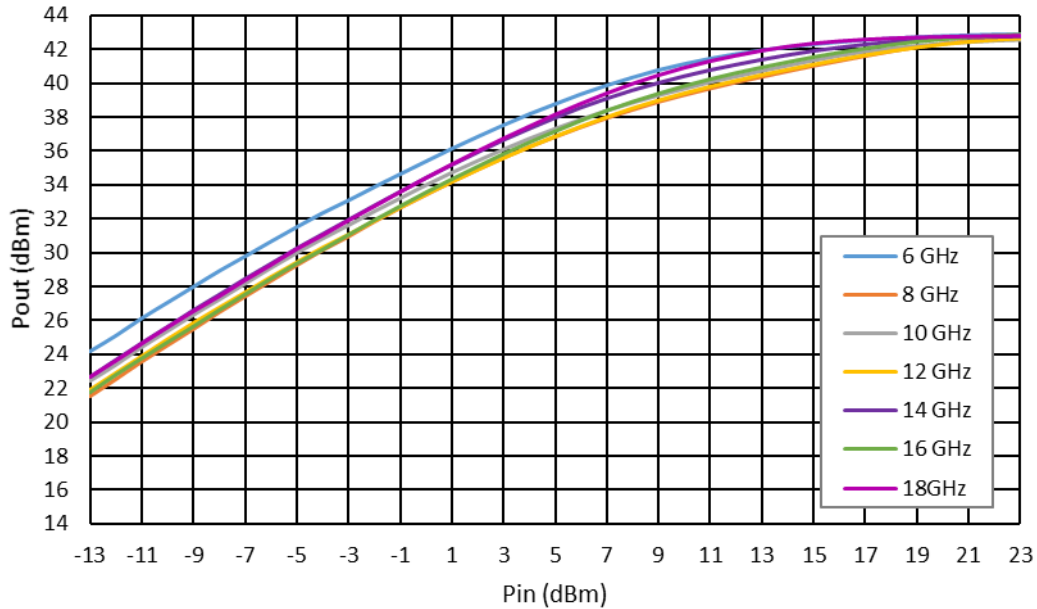
Id (A) versus Frequency (GHz) and temperature variation



Typical Evaluation Board measurements

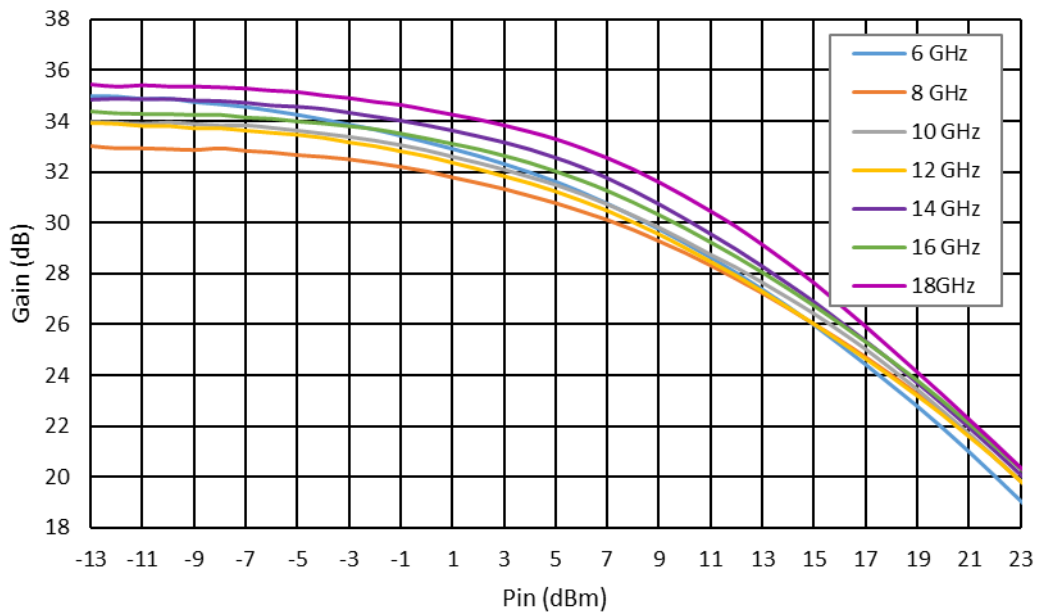
Tbackside = +25°C, Vd = +20V, Idq = 1.2A;

Pout (dBm) vs Pin (dBm) and Frequency



Tbackside = +25°C; Vd = +20V, Idq = 1.2A @ 25°C

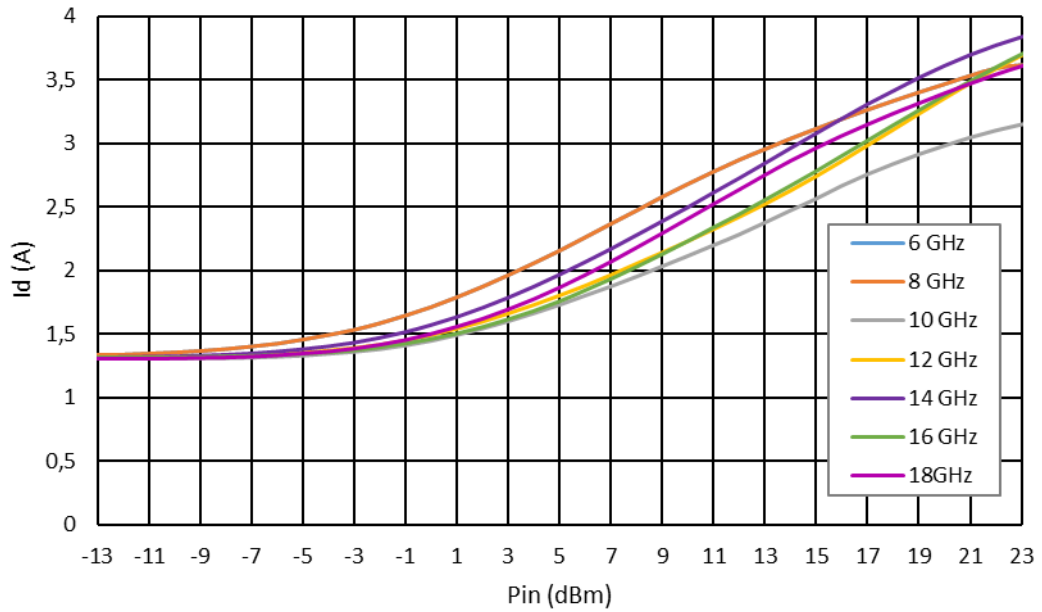
Gain (dB) vs Pin (dBm) and Frequency



Typical Evaluation Board measurements

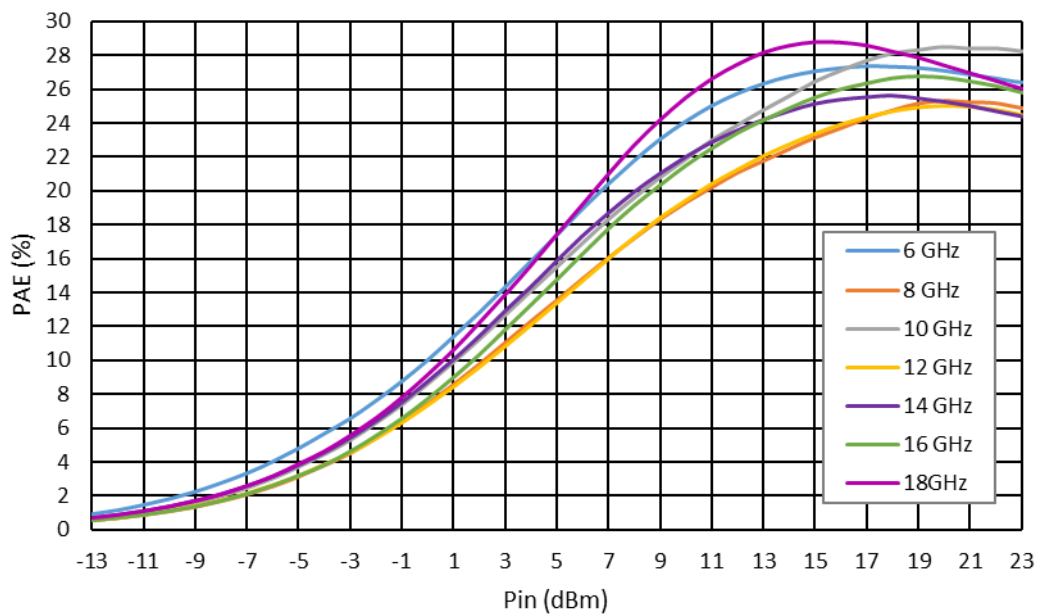
Tbackside = +25°C, Vd = +20V, Idq = 1.2A

Id (A) vs Pin (dBm) and Frequency

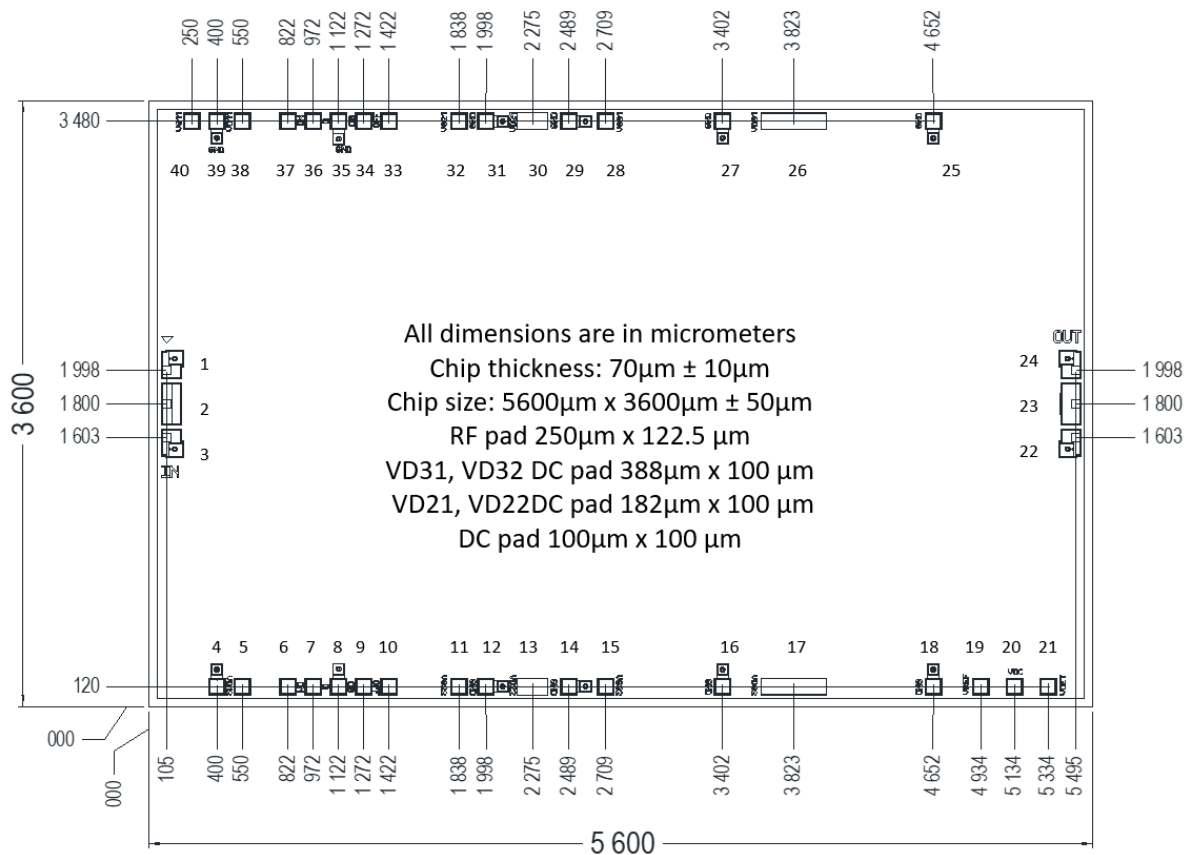


Tbackside = +25°C; Vd = +20, Idq = 1.2A

PAE (%) vs Pin (dBm) and Frequency



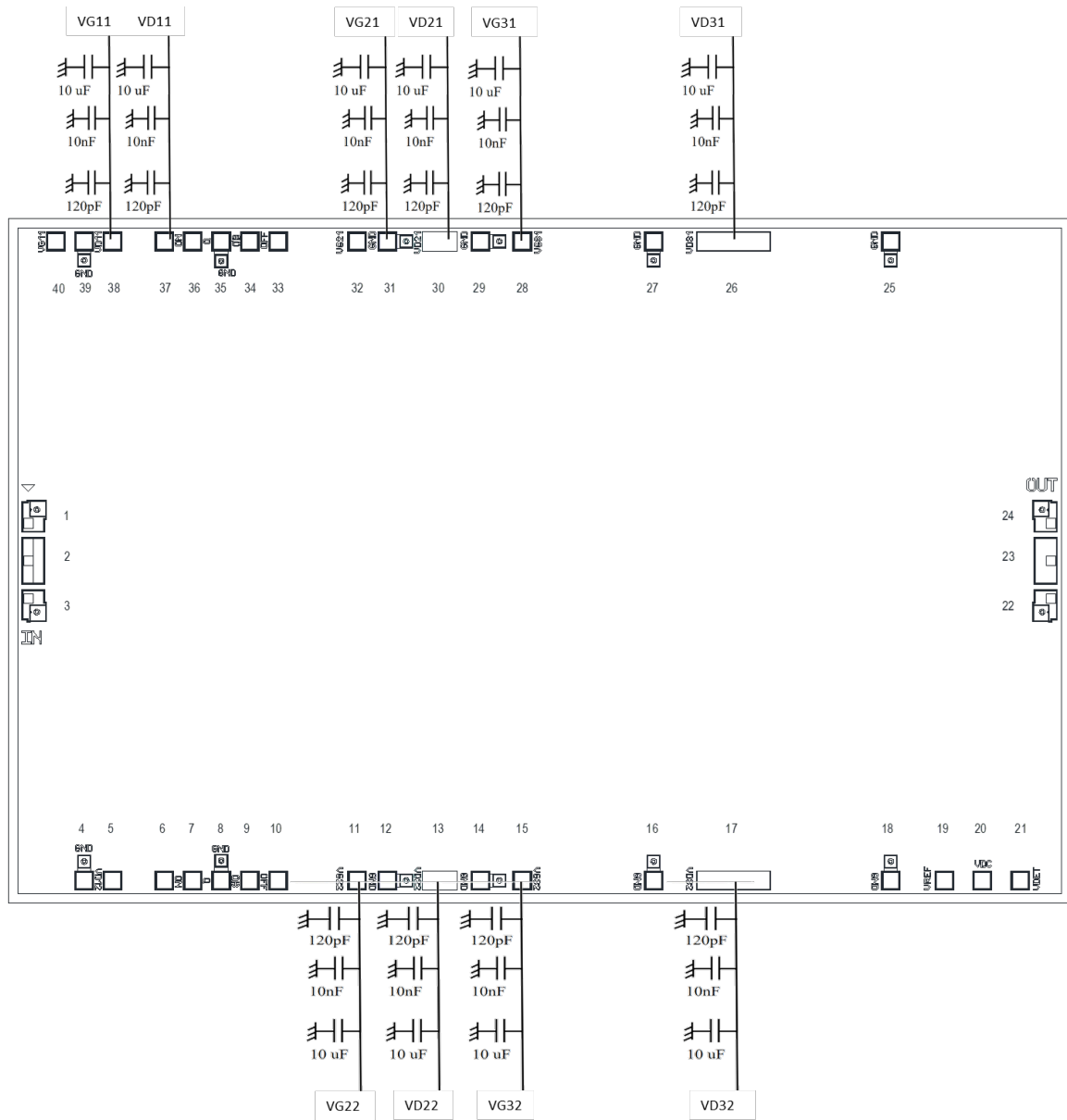
Chip mechanical data



Pad number	Pad name	Pad type	Description
1,3, 22 & 24	GND	GND	
4, 8, 12, 14, 16, 18, 25, 27, 29, 31, 35 & 39	GND	GND	
2	IN	RF IN	RF input signal
23	OUT	RF OUT	RF output signal
40	VG11	Supply	1 st stage gate supply
32, 11	VG21, VG22	Supply	2 nd stage gate supply
28, 15	VG31, VG32	Supply	3 rd stage gate supply
38	VD11	Supply	1 st stage drain supply
30, 13	VD21, VD22	Supply	2 nd stage drain supply
26, 17	VD31, VD32	Supply	3 rd stage drain supply
33	VGOFF		Gate pinch off voltage
34	QB		Gate control voltage
36	Q		Gate control voltage
37	VGON		Gate bias voltage
5	-	Not connected	

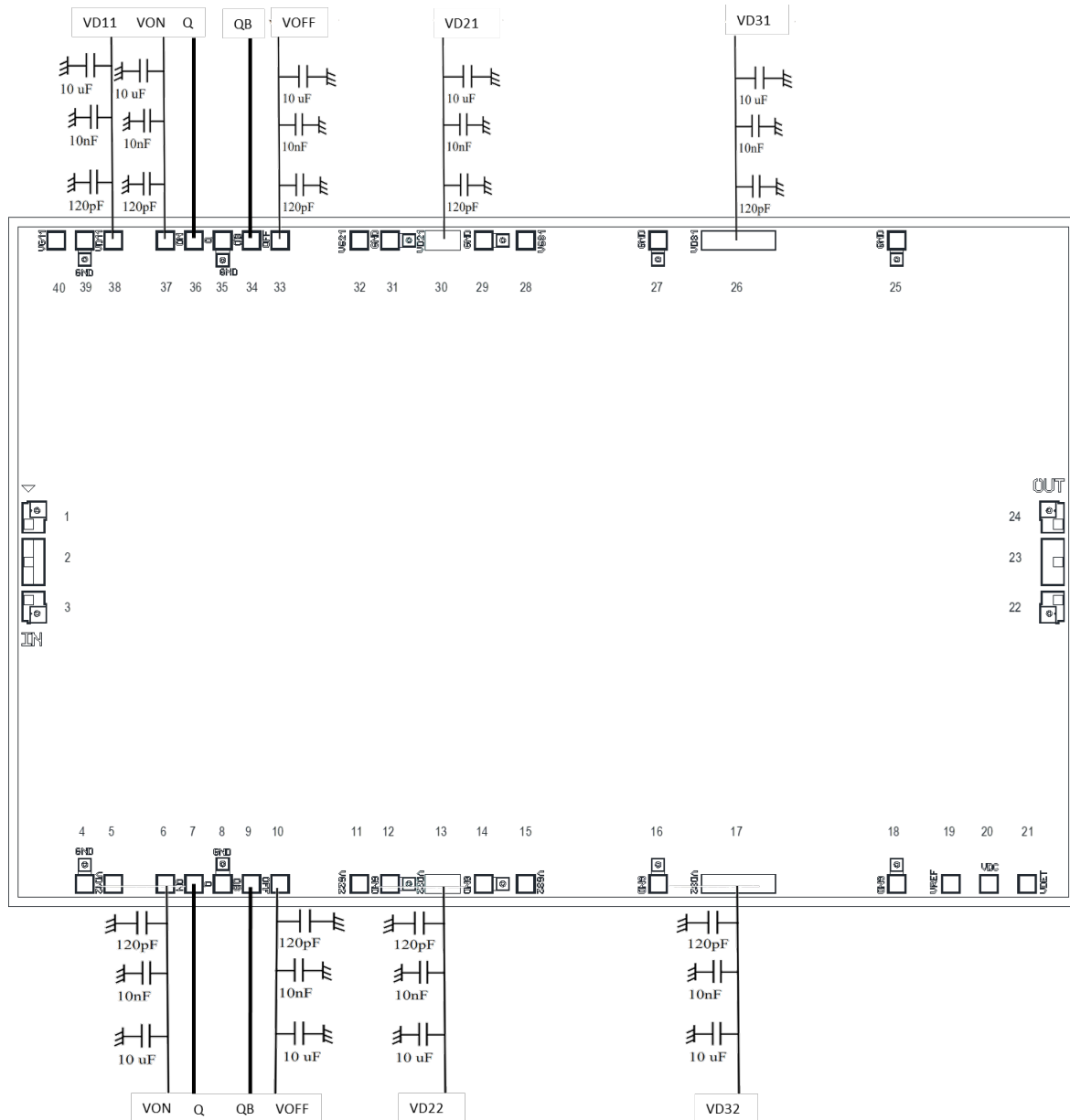
Recommended assembly plan

- Compatible with the proposed footprint.
- Recommended for the implementation of this product on a module board.
- Decoupling capacitors of 120pF, 10nF and 10μF are recommended for all DC accesses.
- See application note AN0030 for details.



Recommended assembly plan by using control interface

- Compatible with the proposed footprint.
- Recommended for the implementation of this product on a module board.
- Decoupling capacitors of 120pF, 10nF and 10μF are recommended for all DC accesses.
- See application note AN0030 for details.

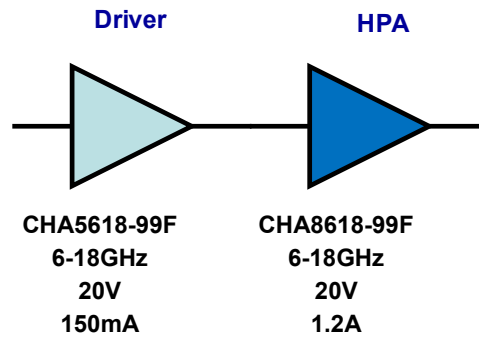


Recommended UMS Power chain

The CHA8618-99F is recommended with the CHA5618-99F as driver.

Total Gain: > 55dB

For more information about the CHA5618-99F, see our web site www.ums-rf.com



Recommended environmental management

UMS products are compliant with the regulation in particular with the directives RoHS N°2011/65 and REACH N°1907/2006. More environmental data are available in the application note AN0019 also available at <https://www.ums-rf.com>.

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Recommended ESD management

Refer to the application note AN0020 available at <https://www.ums-rf.com> for ESD sensitivity and handling recommendations for the UMS products.

Recommended Evaluation board EVB assembly

Refer to the application note AN0030 available at <https://www.ums-rf.com> Evaluation board EVB.

Ordering Information

Chip form:

CHA8618-99F/00

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